

RJ45C5 S1D 2.7N4N RL

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



本製品のラインナップは、下記設計を網羅しています：

- 90アングル（水平）および180ストレート（垂直）
- ラッチアップ/ラッチダウン
- THT、THR、SMDはんだプロセス
- 幅広いデザインタイプ、LED内蔵、シールドタブ付き
- パフォーマンスカテゴリ3 から Cat. Cat.6。
- トレイ包装（TY）またはテープ・オン・リール（RL）
- ANSI / TIA-1096-AおよびIEC 60603に準拠したモジュラーRJ45コネクタに対応
- 絶縁耐力 ≥ 1500 V AC RMS（2250 V ACピーク値）、IEEE 802.3準拠
- IEC 60603に準拠した絶縁耐力 ≥ 1500 V AC（ピーク値）または ≥ 1500 V DC

特性と長所：

- 最大性能に対応する - 40°C から + 85°C の温度範囲拡張
- 30 μ m 金メッキで耐腐食性を強化
- 0.3mm 以上のスタンドオフによる最適なはんだ付け加工

一般注文データ

| | |
|------------|---|
| バージョン | プリント基板用プラグインコネクタ, RJ45ジャック, Cat. 5, SMDはんだ接続, 90°, ラッチオプション: 下部, シールドタブ: なし, 30...80 μ m Ni / ≥ 30 μ m Au, LED: いいえ, 極数: 8, Tape |
| 注文番号 | 1433890000 |
| 種別 | RJ45C5 S1D 2.7N4N RL |
| GTIN (EAN) | 4050118238471 |
| 数量 | 260 Stück |
| パッケージ | Tape |

RJ45C5 S1D 2.7N4N RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

技術データ

寸法と重量

| | | | |
|------------|------------|-----------|------------|
| 深さ | 18.7 mm | 奥行き (インチ) | 0.736 inch |
| 高さ | 16.88 mm | 高さ (インチ) | 0.665 inch |
| 下位バージョンの高さ | 11.8 mm | 幅 | 18.5 mm |
| 幅 (インチ) | 0.728 inch | 正味重量 | 0.007 g |

システム仕様

| | | | |
|---------------|-----------------------------|--------------|----------|
| LED | いいえ | PCB の取り付け | SMDはんだ接続 |
| はんだピン位置の公差 | 0.1 mm | はんだピン寸法 | 八角形 |
| はんだ付け工程 | リフローハンダ付け, 手動 はんだ付け | カテゴリ | Cat. 5 |
| シールド | はい | シールドタブ | なし |
| シールド材質 | 銅合金 | シールド面 | ニッケルメッキ |
| ソルダーピン長 (l) | 3.5 mm | ピッチ (mm) (P) | 1.27 mm |
| ピッチ (インチ) (P) | 0.05 " | ブラギング回数 | 750 |
| ラッチオプション | 下部 | 保護度合い | IP20 |
| 共平面性: | 100 µm | 外向きエルボ | 90° |
| 性能カテゴリ | Cat. 5 | 接続方式 | SMDはんだ接続 |
| 極当たりソルダーピン数 | 1 | 極数 | 8 |
| 製品ファミリー | データの最小化 - RJ45モ ジュラージャック | 配線 | 8コア |

標準

| | |
|--------|----------------|
| コネクタ規格 | IEC 60603-7-51 |
|--------|----------------|

電気プロパティ

| | | | |
|---------------|-----------------|-------------|-----------|
| PoE / PoE+ | IEEE 802.3atに適合 | 定格電圧 | 125 V |
| 定格電流 | 1.5 A | 絶縁耐性 | ≥ 500 MΩ |
| 耐電圧、接点 / シールド | 1500 V DC | 耐電圧、接点 / 接点 | 1000 V DC |

材料データ

| | | | |
|----------------------|------------|-------------|----------------------------|
| 絶縁材 | PA 9T | 色 | 黒色 |
| カラーチャート (類似) | RAL 9011 | 絶縁材グループ | II |
| 比較追跡指数 (CTI) | ≥ 500 | 絶縁耐性 | ≥ 500 MΩ |
| Moisture Level (MSL) | 1 | UL 94 可燃性等級 | V-0 |
| 接点ベース素材 | リン青銅 | 接点材質 | 銅合金 |
| 接触表面 | ニッケル下地金メッキ | プラグ接点の層構造 | 30...80 µ" Ni / ≥ 30 µ" Au |
| 保管温度、最小 | -40 °C | 保管温度、最大 | 85 °C |
| 動作温度、最小 | -40 °C | 動作温度、最大 | 85 °C |

梱包

| | | | |
|--------------|--------|--------|---|
| パッケージ | Tape | VPE 長 | 355 mm |
| VPE幅 | 346 mm | VPEの高さ | 131 mm |
| テーブリール径φ (A) | 330 mm | 表面抵抗 | Rs = 10 ⁹ - 10 ¹² Ω |

作成日 2024/07/02 5:47:38 CEST

RJ45C5 S1D 2.7N4N RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

技術データ

分類

| | | | |
|-------------|-------------|-------------|-------------|
| ETIM 6.0 | EC002637 | ETIM 7.0 | EC002637 |
| ETIM 8.0 | EC002637 | ETIM 9.0 | EC002637 |
| ECLASS 9.0 | 27-44-04-02 | ECLASS 9.1 | 27-44-04-02 |
| ECLASS 10.0 | 27-44-04-02 | ECLASS 11.0 | 27-46-02-01 |
| ECLASS 12.0 | 27-46-02-01 | ECLASS 13.0 | 27-46-02-01 |

環境製品コンプライアンス

REACH SVHC /

承認

ROHS 適合

ダウンロード

| | |
|--------------|--|
| 承認/証明書/適合証明書 | Certificate of Compliance |
| エンジニアリングデータ | CAD data – STEP |
| ユーザ文書 | MAN IE GUIDE DE MAN IE GUIDE EN |
| カタログ | Catalogues in PDF-format |
| ブローシャー | MB FREECONTACT EN FL FIELDWIRING EN PI PROFINET CABLING EN PI PROFINET CABLING EN |

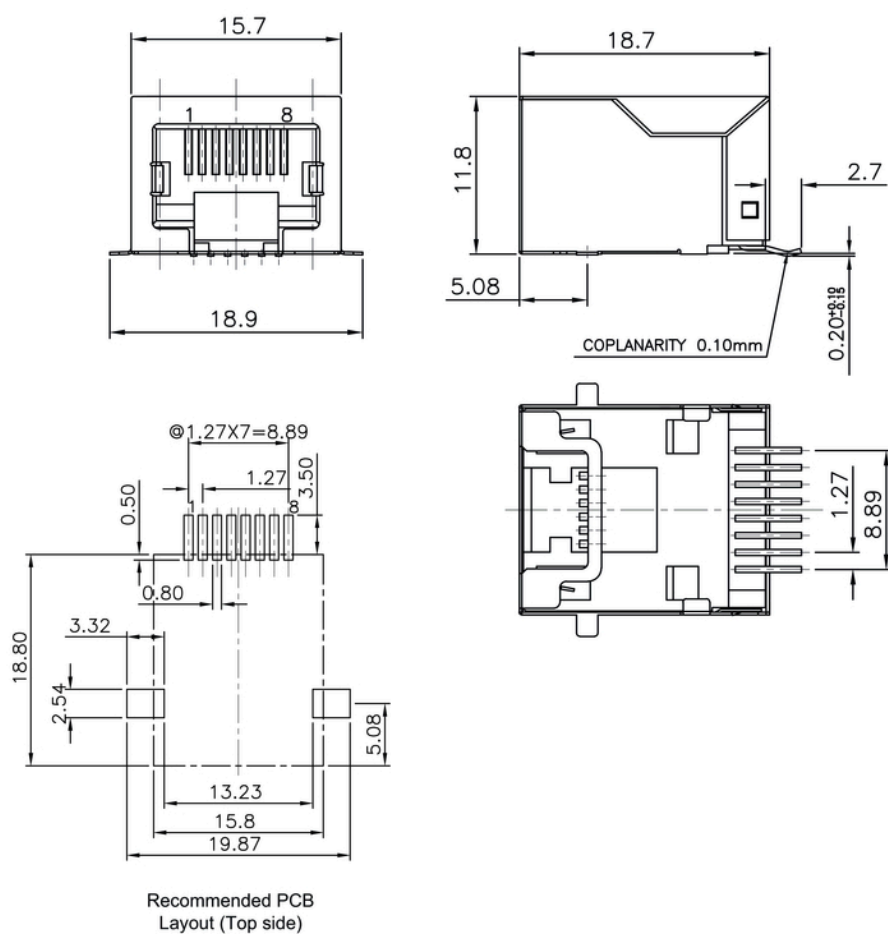
RJ45C5 S1D 2.7N4N RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

図面

寸法図



RJ45C5 S1D 2.7N4N RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

図面

| | | | | | | | | | | |
|------|----|---|---|---|-----|---|---|-------|----|--|
| RJ45 | G1 | R | 1 | U | 3.2 | E | 4 | GY/GY | TY | RJ45G1 R1U 3.2E4GY/GY TY |
| | | | | | | | | | | |
| | | | | | | | | | | Packaging |
| | | | | | | | | | | TY |
| | | | | | | | | | | RL |
| | | | | | | | | | | Tray in box (manual assembly) |
| | | | | | | | | | | Tape on Reel (automated assembly) |
| | | | | | | | | | | LED |
| | | | | | | | | | | Y/G |
| | | | | | | | | | | Green/Yellow (standard) |
| | | | | | | | | | | GY/GY |
| | | | | | | | | | | Green/Yellow/Green-Yellow |
| | | | | | | | | | | O/G |
| | | | | | | | | | | Orange/Green |
| | | | | | | | | | | R/O |
| | | | | | | | | | | Red/Orange |
| | | | | | | | | | | ... |
| | | | | | | | | | | (further combinations possible) |
| | | | | | | | | | | N |
| | | | | | | | | | | without LED |
| | | | | | | | | | | Contact surface thickness |
| | | | | | | | | | | 4 |
| | | | | | | | | | | 1 = 3µ", 2 = 6µ", 3 = 15µ", 4 = 30µ", 5 = 50µ" |
| | | | | | | | | | | EMI tabs (ground fingers) |
| | | | | | | | | | | E |
| | | | | | | | | | | E = with EMI tabs |
| | | | | | | | | | | N |
| | | | | | | | | | | N = without EMI tabs |
| | | | | | | | | | | Solder Pin length |
| | | | | | | | | | | 3.2 |
| | | | | | | | | | | 3.2 mm |
| | | | | | | | | | | 1.6 |
| | | | | | | | | | | 1.6 mm |
| | | | | | | | | | | D |
| | | | | | | | | | | SMD |
| | | | | | | | | | | Direction, latch style |
| | | | | | | | | | | U |
| | | | | | | | | | | Horizontal (90°, side entry), latch up |
| | | | | | | | | | | D |
| | | | | | | | | | | Horizontal (90°, side entry), latch down |
| | | | | | | | | | | V |
| | | | | | | | | | | Vertical (180°, top entry) |
| | | | | | | | | | | Y |
| | | | | | | | | | | Diagonal (45°), latch up |
| | | | | | | | | | | Number of Ports |
| | | | | | | | | | | 1 |
| | | | | | | | | | | 1 Port |
| | | | | | | | | | | 12; 14; ... |
| | | | | | | | | | | multi ports side by side, Multiport |
| | | | | | | | | | | 21; 41; ... |
| | | | | | | | | | | multi ports about each other, Multilevel |
| | | | | | | | | | | Assembly on PCB |
| | | | | | | | | | | R |
| | | | | | | | | | | Through Hole Reflow - THR |
| | | | | | | | | | | Soldering process: Wave or Reflow soldering |
| | | | | | | | | | | S |
| | | | | | | | | | | Surface Mount Technology - SMT |
| | | | | | | | | | | Soldering process: Reflow soldering |
| | | | | | | | | | | T |
| | | | | | | | | | | Through Hole Technology - THT |
| | | | | | | | | | | Soldering process: Wave |
| | | | | | | | | | | Performance Category |
| | | | | | | | | | | C5 |
| | | | | | | | | | | Category 5 |
| | | | | | | | | | | C6 |
| | | | | | | | | | | Category 6 |
| | | | | | | | | | | C6A |
| | | | | | | | | | | Category 6A |
| | | | | | | | | | | C5e |
| | | | | | | | | | | Category 5e |
| | | | | | | | | | | M |
| | | | | | | | | | | 10/100 Mbit |
| | | | | | | | | | | G1 |
| | | | | | | | | | | 10/100/1000 Mbit |
| | | | | | | | | | | G10 |
| | | | | | | | | | | 10 Gbit |
| | | | | | | | | | | U |
| | | | | | | | | | | Unshielded |
| | | | | | | | | | | MP |
| | | | | | | | | | | 10/100 Mbit with POE |
| | | | | | | | | | | MP+ |
| | | | | | | | | | | 10/100 Mbit with POE+ |

凡例

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.